

Assembly Bill of Materials

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Project Name:	Change in menu Project
Project File:	PMP9379 PCB REV1.PrjPCB
Base ID:	XX###
Schematic Rev:	E1
Assembly Variant:	None
Build Quantity:	100
Generated:	6/17/2014 10:43:02 AM

Item	Designator	Description	RoHS	Manufacturer	PartNumber	Quantity	Required	Supplier 1	Supplier Part Number 1	Supplier 2	Supplier Part Number 2	Alternate Manufacturer	Alternate PartNumber
1	IPC8	Printed Circuit Board	O	Any	XX###	1	100						
2	C1, C3, C5, C9, C11, C12	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	Y	AVX	06035C104KAT2A	6	600	Digi-Key	478-5052-1-ND	Mouser	581-06035C104KAT2A	-	-
3	C2, C10	CAP, OS-CON, 150uF, 20V, +/-20%, 0.02 ohm, 10x10.3 SMD	Y	Sanyo	20SVP150M	2	200	Farnell	9189173	Newark	73K4316		
4	C4	CAP, CERM, 4.7uF, 50V, +/-10%, X5R, 1206	Y	MuRata	GRM319R61H475KA12	1	100	Farnell	1845761	Newark	13T1225		
5	C6, C16, C18, C19	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603	Y	TDK	C1608X7R1E105K080AB	4	400	Digi-Key	445-5956-1-ND				
6	C7	CAP, AL, 100uF, 100V, +/-20%, 0.17 ohm, SMD	Y	Panasonic	EEV-FK2A101M	1	100	Digi-Key	PCE3504CT-ND	Mouser	667-EEV-FK2A101M		
7	C8, C13	CAP, CERM, 2.2uF, 6.3V, +/-10%, X5R, 0603	Y	Kemet	C0603C225K9PACTU	2	200	Digi-Key	399-3362-1-ND	Mouser	80-C0603C225K9P		
8	C14, C15	CAP, CERM, 2.2uF, 100V, +/-10%, X7R, 1210	Y	MuRata	GRM32ER72A225KA35L	2	200	Digi-Key	490-3385-1-ND	Mouser	81-GRM32ER72A225KA35		
9	C17	CAP, CERM, 0.1uF, 100V, +/-10%, X7R, 0603	Y	MuRata	GRM188R72A104KA35D	1	100	Digi-Key	490-3285-1-ND	Mouser	81-GRM188R72A104KA35		
10	C20, C21	CAP, CERM, 1000pF, 50V, +/-5%, C0G/NP0, 0603	Y	AVX	06035A101JAT2A	2	200	Digi-Key	478-1175-1-ND	Mouser	581-06035A101J		
11	Cx	CAP, CERM, 1000pF, 100V, +/-5%, X7R, 0603	Y	AVX	06031C102JAT2A	1	100	Digi-Key	478-3698-1-ND	Mouser	581-06031C102J		
12	FID1, FID2, FID3	Fiducial mark. There is nothing to buy or mount.		N/A	N/A	3	300						
13	H1, H2, H3, H4	Machine Screw, Round, #4-40 x 1/4, Nylon, Phillips panhead	Y	B&F Fastener Supply	NY PMS 440 0025 PH	4	400	Digi-Key	H542-ND				
14	H5, H6, H7, H8	Standoff, Hex, 0.5"L #4-40 Nylon	Y	Keystone	1902C	4	400	Digi-Key	1902CK-ND				
15	L1, L2	Inductor, Shielded Drum Core, Ferrite, 47uH, 2.2A, 0.13 ohm, SMD	Y	Coilcraft	MSS1038-473MLB	2	200						
16	LBL1	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	Y	Brady	THT-14-423-10	1	100	Farnell	2065596	Newark	97C5133		
17	R1, R2, R6, R7, R9, R10, R13, R16, R17, R18	RES, 10.0k ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW060310K0FKEA	10	1000	Digi-Key	541-10.0KHCT-ND	Mouser	71-CRCW0603-10K-E3		
18	R3, R15	RES, 140k ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW0603140KFKEA	2	200	Digi-Key	541-140KHCT-ND	Mouser	71-CRCW0603-140K-E3		
19	R4, R5, R11, R12	RES, 100k ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW0603100KFKEA	4	400	Digi-Key	541-100KHCT-ND	Mouser	71-CRCW0603-100K-E3		
20	R8	RES, 49.9k ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW060349K9FKEA	1	100	Digi-Key	541-49.9KHCT-ND	Mouser	71-CRCW0603-49.9K-E3		
21	R14	RES, 66.5k ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW060366K5FKEA	1	100	Digi-Key	541-66.5KHCT-ND	Mouser	71-CRCW0603-66.5K-E3		
22	TP1, TP2	Test Point, Miniature, Yellow, TH	Y	Keystone	5004	2	200	Digi-Key	5004K-ND				
23	TP4, TP5, TP9	Test Point, Multipurpose, Red, TH	Y	Keystone	5010	3	300	Digi-Key	5010K-ND				
24	TP6, TP7, TP8	Test Point, Multipurpose, Black, TH	Y	Keystone	5011	3	300	Digi-Key	5011K-ND				
25	U1, U3	3.5Vin to 60Vin 2A Synchronous Step-Down Voltage Regulator	Used in BOM report. Use Y or N. O	Texas Instruments	LM46002PWP	2	200						
26	U2	Dual Op Amp		National Semiconductor	LM1458M	1	100						

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